SIGMA Co., Ltd.

System Specifications

3D Measurement & Inspection System

3D measurement like Bonding wire, Solder bump and PCB bending etc can be made by one camera with High-speed light sectioning method.

Features

Following inspection can be made by one camera with High-speed light sectioning method.

- 3D Locus of Bonding Wire
- 3D Form of Solder Bump
- Warp of PCB/Ceramics PCB
- 3D Form of Printed Solder Paste
- 3D Form Inspection for Minute Parts
- Co-planarity Inspection for Lead Wire of Electric Components

We can correspond to 3D Measurement & Inspection with Stereo method or Focal Depth method besides Light Sectioning method.
Mechanical part can be designed based on customer's specificaitons.

Exapmle of Application: 3D Inspection of Bonding Wire

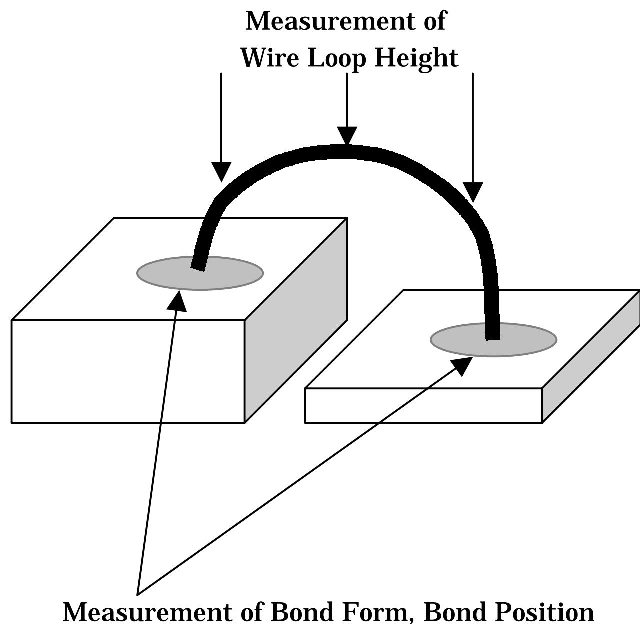
High-speed & high-precision measurement with Light Sectioning method.

Inspection Item

Wire Loop Height, Bonding Form, Length of Tail, Width of Crash, Bonding position, Difference between Left and Right

Specificaitons

1) Wire Loop Height
   ①Accuracy within 50μm
   ②Visual Field 13 x 10 mm
   ③Measurement time
   1~3 sec/visual Field (depends on the number of measurement points)
2) Bonding Form
   ①Accuracy within 5μm
   ②Visual Field 13 x 10 mm
   ③Measurement time 0.5 sec/visual Field
3) Bonding Position
   ①Accuracy within 5μm
   ②Visual Field 13 x 10 mm
   ③Measurement time 0.5 sec/visual Field



About this system, please contact us.

SIGMA Co., Ltd. International Sales Group

TEL +81-42-392-8600 / FAX +81-42-392-5341
E-mail question@sigma-fa.co.jp